

the material of the underlying layer to produce a greater difference between the first and second values with the reactive agent than without the reactive agent; and

stopping removal of material from the substrate when the temperature of the polishing component is at a predetermined value that indicates the material being removed from the planarized surface is at the endpoint of the substrate.

45. The method of claim 44 wherein the act of monitoring a temperature of a polishing component that is in contact with byproducts produced by polishing the substrate comprises monitoring the temperature of the byproducts.

46. The method of claim 45 wherein the act of monitoring the temperature of the byproducts comprises holding the byproducts in a separate cell, adding a reactive agent to the byproducts that detects the presence of material from the underlying layer in the byproducts, and sensing the temperature of the byproducts.

47. The method of claim 44, further comprising sensing the pH of the byproducts.

48. The method of claim 44, further comprising sensing the conductivity of the byproducts.

49. The method of claim 44, further comprising determining the chemical composition of the byproducts. - -

REMARKS

Consideration of this reissue application in view of the above amendments and following remarks is respectfully requested. Applicant is requesting reissue on the basis that the '408 patent is, through error without any deceptive intention, deemed wholly or partially inoperative by reason of the patentee claiming less than he had a right to claim in the '408 patent. For example, claim 1 of the '408 patent is limited to a method for stopping polishing of a

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substrate at a desired endpoint comprising sensing the temperature of byproducts produced from polishing the substrate. However, the applicant has the right to claim at least methods comprising sensing of a characteristic other than temperature to determine the polishing endpoint, and also methods comprising sensing of characteristics of materials other than the byproducts produced during the polishing of the substrate. The assignee offers to surrender the '408 patent once the Examiner has indicated the allowability of all claims associated with this reissue application. The assignee is requesting a reissue of the '408 patent for the invention as disclosed in the '408 patent and claimed in issued claims 1-13 and new claims 14-49.

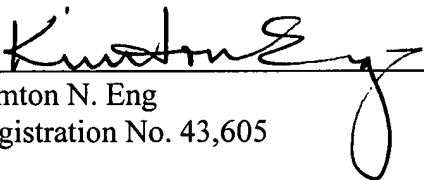
No new matter has been introduced into this application for reissue.

Applicant believes claims 1-49 are in condition for allowance and respectfully requests such action.

If there are any matters that can be handled in a telephone conversation, the Examiner is encouraged to contact Mr. Eng at (206) 903-8718.

Respectfully submitted,

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